

WHAT IS CLAIMED IS:

1. A method of manufacturing a laminated ceramic electronic component comprising the steps of:

preparing a first transfer sheet including a composite green sheet supported by a first supporting film, said composite green sheet having a conductor and at least one of a first ceramic area and a second ceramic area formed in a region excluding a location where the conductor is provided;

preparing a second transfer sheet including a ceramic green sheet supported by a second supporting film;

a first transfer step of transferring the ceramic green sheet of at least one second transfer sheet on a lamination stage;

a second transfer step of transferring the composite green sheet of at least one first transfer sheet on the at least one ceramic green sheet that was previously laminated;

a third transfer step of transferring the ceramic green sheet of at least one second transfer sheet on the composite green sheet that was previously laminated; and

firing a laminate obtained by the first, second and third transfer steps.

2. A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein a plurality of the first transfer sheets are prepared, and the

conductors are formed so that by laminating, the conductors of the plurality of the composite green sheets are electrically connected to form a coil.

3. A method of manufacturing a laminated ceramic electronic component according to claim 2, wherein at least one of the plurality of the conductors is a via hole electrode for connecting the upper and lower conductors.

4. A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein the first ceramic area is made of a magnetic ceramic, and a second ceramic area is made of a non-magnetic ceramic.

5. A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein the ceramic green sheet of the second transfer sheet is made of a magnetic ceramic.

6. A method of manufacturing a laminated ceramic electronic component according to claim 4, further comprising the step of forming the first ceramic area and the second ceramic area by printing a magnetic ceramic paste and a non-magnetic ceramic paste, respectively.

7. A method of manufacturing a laminated ceramic electronic component according to claim 3, further comprising the steps of:

forming the at least one of the first ceramic area and the at least one second ceramic area at a location excluding a region where a via hole electrode is to be formed; and

thereafter filling the region where the via hole is to be formed with an electrically conductive paste to form the via hole electrode.

8. A method of manufacturing a laminated ceramic electronic component according to claim 3, further comprising the steps of:

forming a through hole in which a via hole electrode is to be formed after preparing the composite ceramic green sheet; and

filling the through hole with an electrically conductive paste to form the via hole electrode.

9. A method of manufacturing a laminated ceramic electronic component according to claim 1, further comprising the steps of:

preparing a third transfer sheet in which a second composite green sheet having a magnetic ceramic area and a non-magnetic ceramic area is supported by a third supporting

film; and

transferring the second composite green sheet from at least one third transfer sheet between the first transfer step and the third transfer step.

10. A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein the laminated ceramic electronic component is a closed magnetic circuit type laminated common mode choke coil.

11. A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein the laminated ceramic electronic component is an open magnetic circuit type laminated common mode choke coil.

12. A laminated ceramic electronic component comprising a sintered ceramic body produced according to the method as set forth in claim 1, and a plurality of external electrodes disposed on the outer surface of the sintered ceramic body and electrically connected to the conductors in the sintered ceramic body.

13. A laminated ceramic electronic component according to claim 12, wherein the laminated ceramic electronic component is a closed magnetic circuit type laminated common

mode choke coil.

14. A laminated ceramic electronic component according to claim 12, wherein the laminated ceramic electronic component is an open magnetic circuit type laminated common mode choke coil.

15. A laminated ceramic electronic component comprising:

a sintered ceramic body;

at least one coil conductor arranged in the sintered ceramic body and having a winding portion and first and second lead-out portions; and

a plurality of external electrodes disposed on the outer surface of the sintered ceramic body and electrically connected to an end of the first lead-out portion or an end of the second lead-out portion;

wherein the sintered ceramic body includes a magnetic ceramic and a non-magnetic ceramic, the winding portion of the coil conductor is coated with the non-magnetic ceramic, and the first and second lead-out portions of the coil conductor are coated with the non-magnetic ceramic.

16. A laminated ceramic electronic component according to claim 15, wherein the laminated ceramic electronic

component is a closed magnetic circuit type laminated common mode choke coil.

17. A laminated ceramic electronic component according to claim 15, wherein the laminated ceramic electronic component is an open magnetic circuit type laminated common mode choke coil.

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